

Applied Materials | THIRD QUARTER FISCAL 2026

FINANCIAL OVERVIEW

Q3'26 REVENUE

\$9.12B

↑ 25% YoY

**SEMICONDUCTOR
SYSTEMS**

\$7.04B

↑ 27% YoY

**APPLIED GLOBAL
SERVICES**

\$1.78B

↑ 22% YoY

This document contains forward-looking statements, which are not guarantees of future performance. Risks and uncertainties that could cause our actual results to differ materially from those expressed or implied by such statements include those described in our SEC filings, including our most recent Forms 10-K, 10-Q and 8-K. All forward-looking statements are based on management's current estimates, projections and assumptions, and we assume no obligation to update them.

*For reconciliation of GAAP to non-GAAP results, see the investor relations page at ir.appliedmaterials.com
CY26 refers to FQ2'26-FQ1'27. FQ1'27 will be a 14-week quarter



Non-GAAP Gross Margin*

50.4% ↑ 150bps YoY



Non-GAAP EPS*

\$3.50 ↑ 41% YoY



Cash Flow

\$2.33B in Free Cash Flow*



Shareholder Distributions

\$440M share repurchases
\$420M dividends



Applied Materials delivered another record-breaking quarter, including the highest sequential revenue growth in the company's history. As the rapid global adoption of AI drives unprecedented demand for our materials engineering solutions, we are further raising our Semiconductor Systems revenue expectations for calendar 2026 and are confident we will grow faster than the market this year. Based on the increased demand visibility we are receiving from our customers, we expect another strong growth year for Applied Materials in 2027.

Gary Dickerson,
PRESIDENT AND CEO

KEY THEMES

Record Q3 results with demand strengthening across all leading indicators

- » Record-breaking quarter, including highest QoQ growth in company history
- » 13th straight quarter of YoY gross margin expansion
- » Largest customers providing 8-quarter forecasts which increases demand visibility and enables supply chain readiness

Accelerating AI technology leadership in leading-edge foundry-logic, DRAM and advanced packaging

- » Expect these markets to drive ~80% of WFE growth
- » Announced eight new products spanning deposition, CMP and eBeam
- » Now expect advanced packaging revenue to grow >70% in CY26
- » Record foundry-logic revenue; DRAM, including HBM packaging, up 52% YoY

Helping customers expand capacity while scaling to meet demand

- » Expect AGS to grow >20% in CY26; >37,000 chambers connected to AI^x software
- » Expect process diagnostics and control to grow >50% in CY26
- » New products increase wafer output per square meter of fab space
- » Investing to double quarterly system manufacturing capacity by 2028
- » EPIC partnerships now total 11; EPIC Center to begin operations in the Fall